

ABSTRACT

TITLE OF INVENTION: LIQUID COOLING ASSEMBLY FOR ELECTRONIC COMPONENTS ON PRINTED CIRCUIT BOARDS AND COMPUTING DEVICE INCLUDING SAME

The present invention relates to the technological field of microelectronics and electronic engineering, specifically to advanced liquid-cooling-based thermal management systems for electronic components on printed circuit boards. The claimed invention represents a liquid cooling assembly and a computing device that provide an improvement to the technological field of microelectronics and electronic engineering. Specifically, the suggested solution is easily adjustable to mitigate mechanical tolerances between the different electrical components of the target PCB and adaptable to address the diverse thermal loads presented by them, while maintaining the compactness of the design. The suggested solution thereby increases the overall heat dissipation efficiency of thermal management systems.

[Fig. 1]